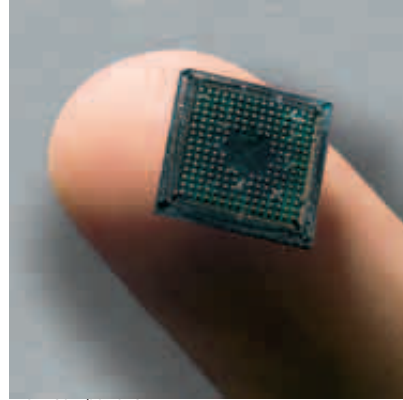


LPKF ZeiPlace BGA



Semi-automatic placement of new generation components to assemble highly integrated circuit boards.



Product description

The placing of components with pins hidden from the top and sides requires reliable and precise alignment to avoid expensive and difficult rework.

LPKF ZeiPlace BGA Placer is designed for the accurate placing of different types of BGA, CSP and flip chip components, as well as fine-pitch and ultra-fine-pitch components. The system is suitable for R&D labs as well as production facilities focusing on custom designs and small batches.

Special optics and adjustable two-colour illumination help to simultaneously view and align the PCB leads and the component pins. Coarse and fine adjustment is achieved using an air-bearing table with micrometer screw adjustment.

As soon as the component is aligned, it is automatically placed at a single push of a button.

Product features

- Semi-automatic placement of BGA and QFQ components from 5 mm x 5 mm (0.2" x 0.2") up to 45 mm x 45 mm (1.77" x 1.77")
- Granite base plate
- Air-bearing positioning table
- Optical placement verification

Specifications LPKF ProtoPlace BGA

Art.-Nr.	111433
Max. PCB size	220 mm x 300 mm (8.6" x 11.8")
Max. size of components	45 mm x 45 mm (1.8" x 1.8")
Min. size of components	5 mm x 5 mm (0.2" x 0.2")
Pitch	0.3 mm (12 mil)
Placement accuracy	± 50 µm (± 2 mil)
Power supply	230 V/50 Hz oder 115 V/60 Hz, 20 VA
Compressed air	6 bar (87 psi), min. 5 l/min (0.18 cfm), oil-free
Dimensions (W/H/D)	600 mm x 430 mm x 435 mm (23.6" x 17" x 17.1")
Weight	35 kg (77 lb)



with CCD camera and monitor